IN THE CLAIMS

Please amend the following claims:

- (Previously amended) A method of forming copper interconnect, comprising:
 forming a copper diffusion barrier layer in at least a damascene structure;
 forming a copper layer over the barrier layer;
 removing a portion of the copper layer by chemical mechanical polishing with a
 slurry comprising a chelating organic acid buffer system, colloidal silica, and a low
 electrochemical potential oxidizer.
- 2. (Original) The method of Claim 1, wherein the oxidizer comprises hydrogen peroxide.
- 3. (Original) The method of Claim 2, wherein the chelating organic acid buffer system comprises citric acid and potassium citrate.
- 4. (Original) The method of Claim 3, wherein the slurry further comprises a corrosion inhibitor.
- 5. (Original) The method of Claim 4, wherein the corrosion inhibitor comprises benzotriazole.
- 6. (Previously amended) A method of forming copper interconnect, comprising: forming a barrier layer over a substrate having at least one trench therein; forming a copper seed layer on the surface of the barrier layer; forming a copper layer over the barrier and seed layers;

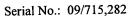
removing a portion of the copper layer by chemical mechanical polishing with a first slurry comprising a chelating organic acid buffer system, colloidal silica, and a low electrochemical oxidizer; and

removing at least a portion of the barrier layer by chemical mechanical polishing with a second slurry comprising a chelating organic acid buffer system, and colloidal silica;

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wherein the second slurry is formed without the oxidizer.

- 7. (Original) The method of Claim 6, wherein the barrier layer comprises tantalum.
- 8. (Original) The method of Claim 7, wherein the chelating organic acid buffer system comprises citric acid and potassium citrate.
- 9. (Original) The method of Claim 8, wherein the oxidizer comprises hydrogen peroxide.
- 10. (Original) The method of Claim 9, wherein the first slurry further comprises a corrosion inhibitor.
- 11. (Original) The method of Claim 10, wherein the first slurry has a pH in the range of 3 to 6, and the corrosion inhibitor comprises benzotriazole.
- 12. (Withdrawn)
- 13. (Withdrawn)
- 14. (Withdrawn)
- 15. (Withdrawn)
- 16. (Withdrawn)
- 17. (Withdrawn)
- 18. (Withdrawn)
- 19. (Withdrawn)
- 20. (Withdrawn)
- 21. (Withdrawn)
- 22 (Withdrawn)
- 23. (Withdrawn)



- 24. (Withdrawn)
- 25. (Withdrawn)
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- 27. (Withdrawn)

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